

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

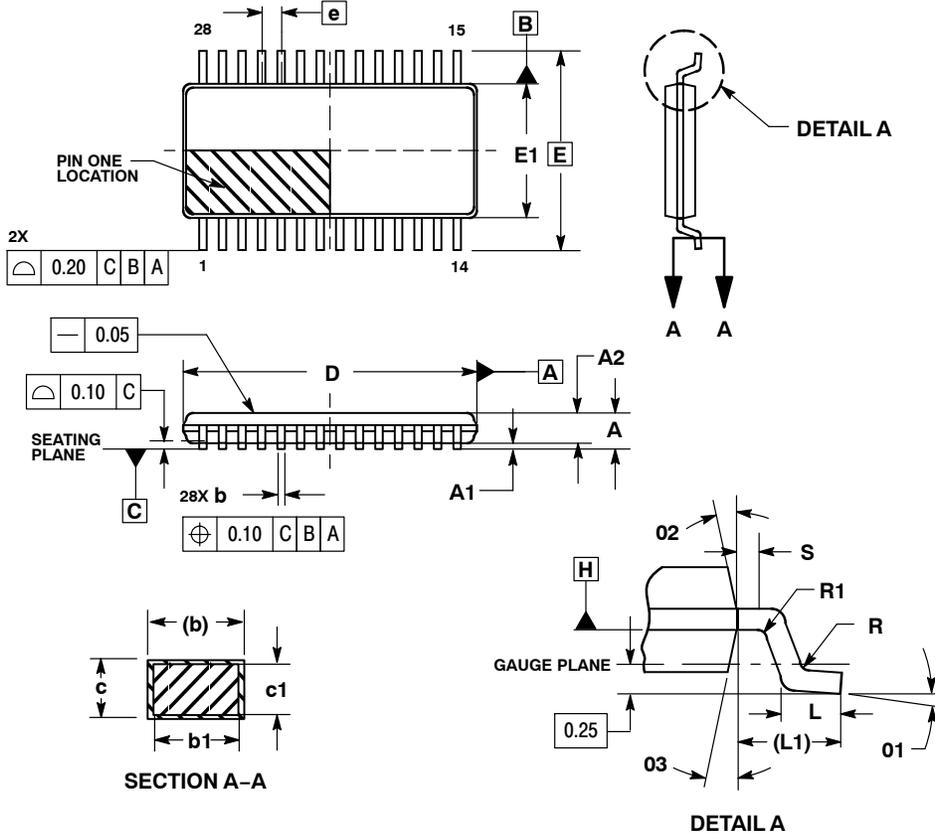
ON Semiconductor®



SCALE 1:1

TSSOP28
CASE 948AA
ISSUE A

DATE 26 OCT 2011

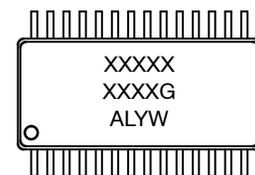


NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. DIMENSIONS IN MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 MM TOTAL IN EXCESS OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION.
4. DATUMS A AND B TO BE DETERMINED AT DATUM PLANE H.

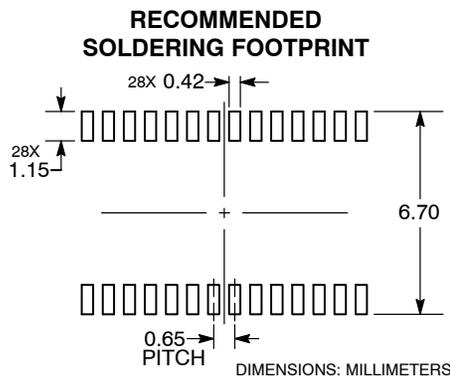
MILLIMETERS		
DIM	MIN	MAX
A	---	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
b1	0.19	0.25
c	0.09	0.20
c1	0.09	0.16
D	9.60	9.80
E	6.40	BSC
E1	4.30	4.50
e	0.65	BSC
L	0.45	0.75
L1	1.00	REF
R	0.09	---
R1	0.09	---
S	0.20	---
01	0°	8°
02	12°	REF
03	12°	REF

GENERIC MARKING DIAGRAM*



- XXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.



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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	28 LEAD TSSOP, 9.7X4.4X1.0 MM, 0.65 PITCH	PAGE 1 OF 2

